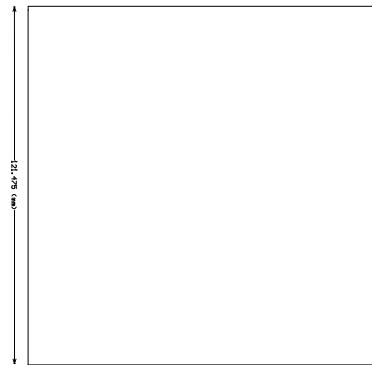


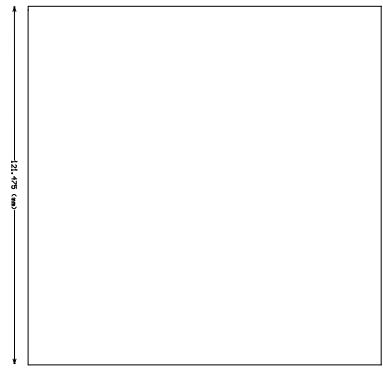
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<p><b>NOTES (UNLESS OTHERWISE SPECIFIED):</b></p> <ol style="list-style-type: none"> <li>1. MAT'L: COPPER CLAD PLATED SHEET PER IPC-4101B/124,       <ol style="list-style-type: none"> <li>a) LAMINATE AND PREPREG TO BE IN ACCORDANCE WITH IPC-4101B/124. MATERIAL MUST MEET UL 94V-0 FLAMMABILITY RATING. THE MATERIAL SHALL BE ROHS COMPLIANT WITH TG OF 150 C MINIMUM AND TD OF 330 C MINIMUM.</li> <li>b) COPPER FOIL TO BE IN ACCORDANCE WITH IPC-MF-150.</li> </ol> </li> <li>2. FINISH COLOR: LIGHT SEE BOARD STACKUP</li> <li>3. TOTAL BOARD THICKNESS OVER MASK: 1.434 MM +/- 10%.</li> <li>2a. UNLESS OTHERWISE SPECIFIED ALL HOLE DIMENSIONS APPLY AFTER PLATING.</li> <li>2b. ALL PLATED THROUGH HOLES TO HAVE A MINIMUM OF .025 MM COPPER.</li> <li>3. ALL HOLES SHALL BE LOCATED WITHIN 0.75 MM DIAMETER OF TRUE POSITION, LAYER TO LAYER REGISTRATION SHALL BE WITHIN .003 . ALL HOLES SURROUNDED BY LAND SHALL HAVE A MINIMUM ANNUAL RING OF 0.1 MM.</li> <li>4. CONDUCTOR WIDTHS AND SPACING SHALL BE WITHIN +/- 10% OF ARTWORK ORIGINALS.</li> <li>5. APPLY SOLDERMASK (LIQUID PHOTO IMAGEABLE) OVER BARE COPPER, SOLDERMASK TO BE PER IPC-SM-840, TYPE B, CLASS 3, TRANSPARENT GREEN, ALL EXPOSED CONDUCTIVE SURFACES TO BE IMMERSION GOLD (ENIG). TENSILE ALL DIRECTIONS.</li> <li>6. LEAD FREE THT HOLES SHALL NOT EXCEED .10 INCH PER INCH.</li> <li>7. SILKSCREEN COMPONENT SITES (TOP AND BOTTOM) USING BLUE NON-CONDUCTIVE INK. SILKSCREEN TO BE CRISP AND LEGIBLE. DO NOT CLIP SILKSCREEN OVER MASKED VIAS.</li> <li>8. REMOVE ALL BURRS AND BREAK SHARP EDGES 0.4 MM MAX.</li> <li>9. BOARD SHALL MEET THE REQUIREMENTS OF UL796 WITH A FLAMMABILITY RATING OF 94V-0. VENDOR'S UL LOGO OR DESIGNATION SHALL BE LOCATED ON SOLDEN SIDE OF BOARD.</li> <li>10. FABRICATE IN ACCORDANCE WITH IPC-6012, CLASS 2.</li> <li>11. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.</li> <li>12. SURFACE MOUNT PAD SOLDER PLATING MUST BE FLAT TO A MAXIMUM OF .003 MM ABOVE BOARD SURFACE.</li> <li>13. DEFECTIVE BOARDS ON A PANEL SHALL BE MARKED WITH A BLACK X , COVERING 80% OR MORE OF THE BOARD.</li> <li>14. OK TO REMOVE NON-FUNCTIONAL PADS ON INNER LAYERS.</li> <li>15. VIA THERMALS ON PLANE LAYERS CAN BE REMOVED FOR DIRECT CONNECTION.</li> <li>** 16. CONTROLLED IMPEDANCE DIFF TRACES ON ALL LAYERS, EXCEPT L7_NonCritical</li> <li>17. IT IS AT THE DISCRETION OF THE FABRICATOR TO BLOCK MASK FINE PITCH PADS.</li> <li>18. SILKSCREEN COLOUR SHALL BE WHITE.</li> </ol>																																																																																														
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